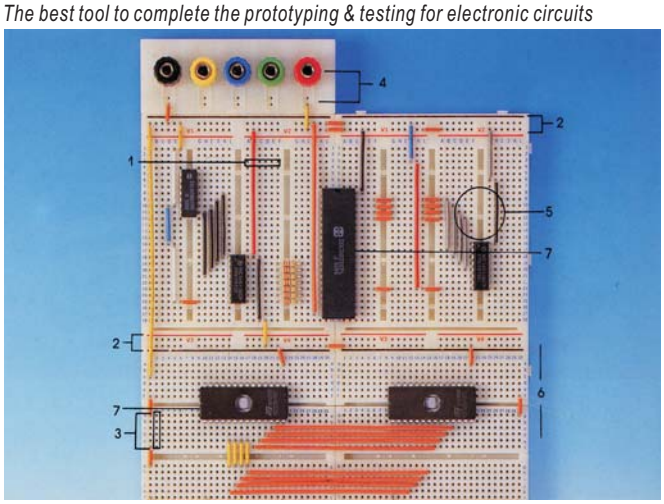
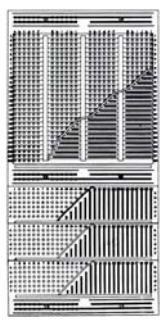
Advanced Solderless Breadboard

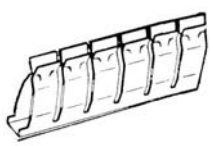
The best tool to complete the prototyping & testing for electronic circuits



1. 6 interconnected round tie points per row in horizontal array provide an ideal placement and more tie points for MSI, LSI and all DIP size chips in "CPU BUS" connection.
2. POWER BUS
   2 of 24 each of continual interconnected tie points with black line printing 4 of 12 each of continual interconnected tie points with red line printing & V1, V2, V3, V4 marking individually
3. 6 interconnected round tie points per column in vertical array provide an ideal placement and wiring for NON-DIP size components.
4. Power block provides 5 individual binding post for easy connection of power bus. (Accept 4.5mm Y-terminal, stripped wire and 4mm banana plug.)
5. Interconnected "Round" tie points make your wiring easier. Accept solid wires from AWG # 22-30 (0.3-0.8 mm).
6. Vertical combination will offer more wiring spaces for DIP size components.
7. The IC chips can be mounted between two AD breadboards when combination.



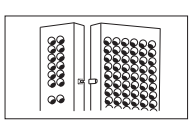
- More interconnected tie points
- Better structure
- More terminals & power bus
- Easy combination & expansion
- Easy insertion & wiring
- Very flexible for digital & analog circuits

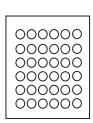


AD Series

Material

- External Body is made of ABS.
- The internal interconnected clips are Nickel-Plated or Silver-Plated.


SNAP LOCK


ROUND HOLE

N:NICKEL PLATED S:SILVER PLATED

Specification

MODEL	DIMENSION(m/m)			TIE-POINTS	6 interconnected CLIP	12 interconnected CLIP	24 interconnected CLIP	BINDING POST	BACK-PLATE	WEIGHT (gm)
	LENGTH	WIDTH	HEIGHT							
AD-4D	81	12	9	48	0	2	1	0	STICKER	10
AD-100	81	42	9	360	60	0	0	0	STICKER	30
AD-101	81	52	9	408	60	2	1	0	STICKER	40
AD-102	81	62	9	456	60	4	2	0	STICKER	50
AD-10	81	30	19	10	0	0	0	5	STICKER	20.4
AD-01	83	118	9	948	142	4	2	0	STICKER	77.8
AD-11	83	147	19	958	142	4	2	5	STICKER	98.8
AD-12	184	168	24	1906	284	8	4	5	ABS plastic	254.4
AD-13	266	168	24	2854	426	12	6	5	ABS plastic	367.6
AD-14	346	168	24	3802	568	16	8	5	ABS plastic	490.0